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**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION**

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**13-Jul-2009**

**SUBJECT: ON Semiconductor Final Product/Process Change Notification #16300**

**TITLE: Final Notification for Transfer of High Speed Logic Integrated Circuits Die Manufacturing From ON Semiconductor Piestany (Slovakia) To Tower Semiconductor Ltd. (Israel).**

**PROPOSED FIRST SHIP DATE: 12-Oct-2009**

**AFFECTED CHANGE CATEGORY(S): ON Semiconductor Fab Site**

**AFFECTED PRODUCT DIVISION(S): Standard Logic Products**

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or Sean Clark <[ffthgm@onsemi.com](mailto:ffthgm@onsemi.com)>

**SAMPLES:** Contact your local ON Semiconductor Sales Office

**ADDITIONAL RELIABILITY DATA:** Available 3Q 2009

Contact your local ON Semiconductor Sales Office or Matt Kas <[Matt.Kas@onsemi.com](mailto:Matt.Kas@onsemi.com)>

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

**DESCRIPTION AND PURPOSE:**

This is the FPCN16300 to IPCN16178 available at [www.onsemi.com](http://www.onsemi.com) ON Semiconductor.

As previously publically announced:

**May 14, 2008** - ON Semiconductor (Nasdaq: ONNN), has announced plans to close its two wafer manufacturing facilities located in Piestany, Slovakia, and transfer the production lines to other facilities. The targeted close date is Q4 2009.

Description of the change:

The transfer and qualification of the High Speed Logic CMOS process and the associated integrated circuits from the ON Semiconductor Piestany facility (Slovakia) to the Tower Semiconductor Ltd. wafer fabrication site located in Migdal Haemek, Israel.

The Tower Semiconductor Ltd Migdal Haemek, Israel fab is certified according to ISO/TS16949 standard.

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The High Speed Logic process is a CMOS technology being replicated at Tower Semiconductor Ltd. to get the same electrical and reliability performances as the Piestany wafer fab.

Assembly of SOIC, SOIC Wide and TSSOP packages will also be converted at the same time from gold wire bond to copper wire bond. Other packages for High Speed Logic will continue to use gold wire bond; these packages include PDIP and QFN. The qualification plan includes the requirement to validate both the fab transfer and conversion to copper wire bond altogether.

The integrated circuits electrical specifications will remain identical. A full electrical characterization over the temperature range will be performed for each product to check the device functionality and electrical specifications.

Qualification tests are designed to show that the reliability of transferred devices will continue to meet or exceed ON Semiconductor standards. ON Semiconductor recommends that customers evaluate sample units in each associated application circuit to ensure there are no unexpected electrical incompatibilities.

The High Speed Logic process has been qualified at Tower Semiconductor Ltd. All products are expected to be available by the end of 4Q2009. Samples will be available beginning July 2009.

**QUALIFICATION PLAN****Product Qualification Vehicles**

The product qualification vehicles represent the broadest use of possible design library elements and available process modules. The following qualification vehicles were selected for this qualification

MC74HC4051  
MC74HC4066  
MC74HC245  
NLSF1174

Qualification of each transfer device type transferred was performed to the following requirements:  
Five temperature electrical characterization  
ESD testing Human Body Model and Machine Model  
Latch up testing

**Final Product/Process Change Notification #16300****RELIABILITY DATA SUMMARY:****Reliability Test Results:**

<b>Test</b>	<b>Conditions</b>		<b>Results</b>
Early Life (ELFR)	Ta=+125°C, Bias	48hrs	0/4800
High Temp. Operating Life Life (HTOL)	Ta=+125°C, Bias	1008hrs	0/539
Temp. Cycle (TC)*	-65°C to +150°C	500 cycles	0/539
Autoclave (AC)*	+121°C /15psig/100%RH	96hrs	0/539
High Temp Storage Life (HTSL)	+150°C	504hrs	0/539
High Accelerated Stress Test* (HAST)	+130°C/85%RH Bias	96hrs	0/539
Wire Bond Pull Strength (BPS)	30 bonds/5 units		CPK > 1.33 Pass
Wire Bond Shear Strength (BS)	30 bonds/5 units		CPK > 1.33 Pass

\*Note: These tests may be performed with pre-conditioned parts depending upon the device type used.

**CHARACTERIZATION RESULTS**

DC, AC, ESD, and Latch-up testing was performed on the qualification vehicles and compared to historical data for each device. Characterization results on all qualification devices matched historical data. Characterization results are available for review upon request.

**CHANGED PART IDENTIFICATION**

There will be no changes to standard device markings. Normal assembly lots traceability codes will identify the wafer fab source.



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**AFFECTED DEVICE LIST**

- MC74HC00ADG
- MC74HC00ADR2
- MC74HC00ADR2G
- MC74HC00ADTR2
- MC74HC00ADTR2G
- MC74HC00AN
- MC74HC00ANG
- MC74HC02AD
- MC74HC02ADG
- MC74HC02ADR2
- MC74HC02ADR2G
- MC74HC02ADTR2
- MC74HC02ADTR2G
- MC74HC02AN
- MC74HC02ANG
- MC74HC03ADG
- MC74HC03ADR2
- MC74HC03ADR2G
- MC74HC03ADTR2
- MC74HC03ADTR2G
- MC74HC03ANG
- MC74HC04AD
- MC74HC04ADG
- MC74HC04ADR2
- MC74HC04ADR2G
- MC74HC04ADTR2
- MC74HC04ADTR2G
- MC74HC04AN
- MC74HC04ANG
- MC74HC08AD
- MC74HC08ADG
- MC74HC08ADR2
- MC74HC08ADR2G
- MC74HC08ADTR2
- MC74HC08ADTR2G
- MC74HC08AN
- MC74HC08ANG
- MC74HC125AD
- MC74HC125ADG
- MC74HC125ADR2
- MC74HC125ADR2G
- MC74HC125ADT
- MC74HC125ADTG
- MC74HC125ADTR2
- MC74HC125ADTR2G
- MC74HC125AN
- MC74HC125ANG
- MC74HC126ADG
- MC74HC126ADR2



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**AFFECTED DEVICE LIST**

- MC74HC126ADR2G
- MC74HC126ADTR2
- MC74HC126ADTR2G
- MC74HC126ANG
- MC74HC132AD
- MC74HC132ADG
- MC74HC132ADR2
- MC74HC132ADR2G
- MC74HC132ADT
- MC74HC132ADTG
- MC74HC132ADTR2
- MC74HC132ADTR2G
- MC74HC132AN
- MC74HC132ANG
- MC74HC138AD
- MC74HC138ADG
- MC74HC138ADR2
- MC74HC138ADR2G
- MC74HC138ADTR2
- MC74HC138ADTR2G
- MC74HC138AN
- MC74HC138ANG
- MC74HC139ADG
- MC74HC139ADR2
- MC74HC139ADR2G
- MC74HC139ADR2H
- MC74HC139ADTR2
- MC74HC139ADTR2G
- MC74HC139AN
- MC74HC139ANG
- MC74HC14AD
- MC74HC14ADG
- MC74HC14ADR2
- MC74HC14ADR2G
- MC74HC14ADT
- MC74HC14ADTG
- MC74HC14ADTR2
- MC74HC14ADTR2G
- MC74HC14AN
- MC74HC14ANG
- MC74HC157ADG
- MC74HC157ADR2
- MC74HC157ADR2G
- MC74HC157ADTR2
- MC74HC157ADTR2G
- MC74HC157AN
- MC74HC157ANG
- MC74HC164ADG
- MC74HC164ADR2



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**AFFECTED DEVICE LIST**

- MC74HC164ADR2G
- MC74HC164ADTR2
- MC74HC164ADTR2G
- MC74HC164AN
- MC74HC164ANG
- MC74HC165AD
- MC74HC165ADG
- MC74HC165ADR2
- MC74HC165ADR2G
- MC74HC165ADTR2
- MC74HC165ADTR2G
- MC74HC165AN
- MC74HC165ANG
- MC74HC174ADG
- MC74HC174ADR2
- MC74HC174ADR2G
- MC74HC174ADTR2
- MC74HC174ADTR2G
- MC74HC174ANG
- MC74HC175ADG
- MC74HC175ADR2
- MC74HC175ADR2G
- MC74HC175ADTR2
- MC74HC175ADTR2G
- MC74HC175ANG
- MC74HC240ADTR2
- MC74HC240ADTR2G
- MC74HC240ADWG
- MC74HC240ADWR2
- MC74HC240ADWR2G
- MC74HC240AN
- MC74HC240ANG
- MC74HC244ADTG
- MC74HC244ADTR2
- MC74HC244ADTR2G
- MC74HC244ADW
- MC74HC244ADWG
- MC74HC244ADWR2
- MC74HC244ADWR2G
- MC74HC244AN
- MC74HC244ANG
- MC74HC245ADT
- MC74HC245ADTG
- MC74HC245ADTR2
- MC74HC245ADTR2G
- MC74HC245ADW
- MC74HC245ADWG
- MC74HC245ADWR2
- MC74HC245ADWR2G



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**AFFECTED DEVICE LIST**

- MC74HC245AN
- MC74HC245ANG
- MC74HC273ADT
- MC74HC273ADTG
- MC74HC273ADTR2
- MC74HC273ADTR2G
- MC74HC273ADW
- MC74HC273ADWG
- MC74HC273ADWR2
- MC74HC273ADWR2G
- MC74HC273AN
- MC74HC273ANG
- MC74HC32AD
- MC74HC32ADG
- MC74HC32ADR2
- MC74HC32ADR2G
- MC74HC32ADTR2
- MC74HC32ADTR2G
- MC74HC32AN
- MC74HC32ANG
- MC74HC373ADT
- MC74HC373ADTG
- MC74HC373ADTR2
- MC74HC373ADTR2G
- MC74HC373ADW
- MC74HC373ADWG
- MC74HC373ADWR2
- MC74HC373ADWR2G
- MC74HC373AN
- MC74HC373ANG
- MC74HC374ADT
- MC74HC374ADTG
- MC74HC374ADTR2
- MC74HC374ADTR2G
- MC74HC374ADW
- MC74HC374ADWG
- MC74HC374ADWR2
- MC74HC374ADWR2G
- MC74HC374AN
- MC74HC374ANG
- MC74HC390ADG
- MC74HC390ADR2
- MC74HC390ADR2G
- MC74HC390ADTR2
- MC74HC390ADTR2G
- MC74HC390ANG
- MC74HC393ADG
- MC74HC393ADR2
- MC74HC393ADR2G



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**AFFECTED DEVICE LIST**

- MC74HC393ADTR2
- MC74HC393ADTR2G
- MC74HC393ANG
- MC74HC4020ADG
- MC74HC4020ADR2
- MC74HC4020ADR2G
- MC74HC4020ADTR2
- MC74HC4020ADTR2G
- MC74HC4020AN
- MC74HC4020ANG
- MC74HC4040AD
- MC74HC4040ADG
- MC74HC4040ADR2
- MC74HC4040ADR2G
- MC74HC4040ADTR2
- MC74HC4040ADTR2G
- MC74HC4040AN
- MC74HC4040ANG
- MC74HC4046AD
- MC74HC4046ADG
- MC74HC4046ADR2
- MC74HC4046ADR2G
- MC74HC4046ADT
- MC74HC4046ADTG
- MC74HC4046ADTR2
- MC74HC4046ADTR2G
- MC74HC4046AN
- MC74HC4046ANG
- MC74HC4051ADG
- MC74HC4051ADR2
- MC74HC4051ADR2G
- MC74HC4051ADR2H
- MC74HC4051ADT
- MC74HC4051ADTG
- MC74HC4051ADTR2
- MC74HC4051ADTR2G
- MC74HC4051ADW
- MC74HC4051ADWG
- MC74HC4051ADWR2
- MC74HC4051ADWR2G
- MC74HC4051AN
- MC74HC4051ANG
- MC74HC4052ADG
- MC74HC4052ADR2
- MC74HC4052ADR2G
- MC74HC4052ADT
- MC74HC4052ADTG
- MC74HC4052ADTR2
- MC74HC4052ADTR2G





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**AFFECTED DEVICE LIST**

- MC74HC4052ADWG
- MC74HC4052ADWR2
- MC74HC4052ADWR2G
- MC74HC4052AN
- MC74HC4052ANG
- MC74HC4053ADG
- MC74HC4053ADR2
- MC74HC4053ADR2G
- MC74HC4053ADT
- MC74HC4053ADTG
- MC74HC4053ADTR2
- MC74HC4053ADTR2G
- MC74HC4053ADWG
- MC74HC4053ADWR2
- MC74HC4053ADWR2G
- MC74HC4053ANG
- MC74HC4060ADG
- MC74HC4060ADR2
- MC74HC4060ADR2G
- MC74HC4060ADT
- MC74HC4060ADTG
- MC74HC4060ADTR2
- MC74HC4060ADTR2G
- MC74HC4060AN
- MC74HC4060ANG
- MC74HC4066AD
- MC74HC4066ADG
- MC74HC4066ADR2
- MC74HC4066ADR2G
- MC74HC4066ADR2H
- MC74HC4066ADTR2
- MC74HC4066ADTR2G
- MC74HC4066ANG
- MC74HC4316ADR2
- MC74HC4316ADR2G
- MC74HC4316ANG
- MC74HC4538AD
- MC74HC4538ADG
- MC74HC4538ADR2
- MC74HC4538ADR2G
- MC74HC4538ADTR2
- MC74HC4538ADTR2G
- MC74HC4538AN
- MC74HC4538ANG
- MC74HC4851AD
- MC74HC4851ADG
- MC74HC4851ADR2
- MC74HC4851ADR2G
- MC74HC4851ADTR2



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**AFFECTED DEVICE LIST**

- MC74HC4851ADTR2G
- MC74HC4851ADWR2
- MC74HC4851ADWR2G
- MC74HC4851ANG
- MC74HC4852ADG
- MC74HC4852ADR2
- MC74HC4852ADR2G
- MC74HC4852ADTR2
- MC74HC4852ADTR2G
- MC74HC4852ANG
- MC74HC540ADTR2
- MC74HC540ADTR2G
- MC74HC540ADWG
- MC74HC540ADWR2
- MC74HC540ADWR2G
- MC74HC540ANG
- MC74HC541ADT
- MC74HC541ADTG
- MC74HC541ADTR2
- MC74HC541ADTR2G
- MC74HC541ADW
- MC74HC541ADWG
- MC74HC541ADWR2
- MC74HC541ADWR2G
- MC74HC541AN
- MC74HC541ANG
- MC74HC573ADT
- MC74HC573ADTG
- MC74HC573ADTR2
- MC74HC573ADTR2G
- MC74HC573ADW
- MC74HC573ADWG
- MC74HC573ADWR2
- MC74HC573ADWR2G
- MC74HC573AN
- MC74HC573ANG
- MC74HC574ADTR2
- MC74HC574ADTR2G
- MC74HC574ADW
- MC74HC574ADWG
- MC74HC574ADWR2
- MC74HC574ADWR2G
- MC74HC574AN
- MC74HC574ANG
- MC74HC589AD
- MC74HC589ADG
- MC74HC589ADR2
- MC74HC589ADR2G
- MC74HC589ADTR2



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**AFFECTED DEVICE LIST**

- MC74HC589ADTR2G
- MC74HC589AN
- MC74HC589ANG
- MC74HC595AD
- MC74HC595ADG
- MC74HC595ADH
- MC74HC595ADR2
- MC74HC595ADR2G
- MC74HC595ADR2H
- MC74HC595ADT
- MC74HC595ADTG
- MC74HC595ADTR2
- MC74HC595ADTR2G
- MC74HC595ADTR2H
- MC74HC595AN
- MC74HC595ANG
- MC74HC74AD
- MC74HC74ADG
- MC74HC74ADR2
- MC74HC74ADR2G
- MC74HC74ADTR2
- MC74HC74ADTR2G
- MC74HC74AN
- MC74HC74ANG
- MC74HC86AD
- MC74HC86ADG
- MC74HC86ADR2
- MC74HC86ADR2G
- MC74HC86ADTR2
- MC74HC86ADTR2G
- MC74HC86ANG
- MC74HCT04ADG
- MC74HCT04ADR2
- MC74HCT04ADR2G
- MC74HCT04ADTR2
- MC74HCT04ADTR2G
- MC74HCT04ANG
- MC74HCT138ANG
- MC74HCT14ADG
- MC74HCT14ADR2
- MC74HCT14ADR2G
- MC74HCT14ADR2GH
- MC74HCT14ADTR2
- MC74HCT14ADTR2G
- MC74HCT14ANG
- MC74HCT244ADTR2
- MC74HCT244ADTR2G
- MC74HCT244ADWG
- MC74HCT244ADWR2



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**AFFECTED DEVICE LIST**

- MC74HCT244ADWR2G
- MC74HCT244AN
- MC74HCT244ANG
- MC74HCT245ADTG
- MC74HCT245ADTR2
- MC74HCT245ADTR2G
- MC74HCT245ADW
- MC74HCT245ADWG
- MC74HCT245ADWR2
- MC74HCT245ADWR2G
- MC74HCT245AN
- MC74HCT245ANG
- MC74HCT273ADTR2
- MC74HCT273ADTR2G
- MC74HCT273ADWG
- MC74HCT273ADWR2G
- MC74HCT273ANG
- MC74HCT373ADTR2
- MC74HCT373ADTR2G
- MC74HCT373ADWG
- MC74HCT373ADWR2
- MC74HCT373ADWR2G
- MC74HCT373ANG
- MC74HCT374ADTR2
- MC74HCT374ADTR2G
- MC74HCT374ADTR2H
- MC74HCT374ADWG
- MC74HCT374ADWR2
- MC74HCT374ADWR2G
- MC74HCT374ANG
- MC74HCT541ADTR2
- MC74HCT541ADTR2G
- MC74HCT541ADWG
- MC74HCT541ADWR2
- MC74HCT541ADWR2G
- MC74HCT541ANG
- MC74HCT573ADTR2
- MC74HCT573ADTR2G
- MC74HCT573ADWG
- MC74HCT573ADWR2
- MC74HCT573ADWR2G
- MC74HCT573ANG
- MC74HCT574ADTR2
- MC74HCT574ADTR2G
- MC74HCT574ADWG
- MC74HCT574ADWR2
- MC74HCT574ADWR2G
- MC74HCT574ANG
- MC74HCT74ADG



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**AFFECTED DEVICE LIST**

- MC74HCT74ADR2
- MC74HCT74ADR2G
- MC74HCT74ANG
- MC74HCU04ADG
- MC74HCU04ADR2
- MC74HCU04ADR2G
- MC74HCU04ADTR2
- MC74HCU04ADTR2G
- MC74HCU04ANG
- MC74VHC4051DR2
- MC74VHC4051DR2G
- MC74VHC4051DTR2
- MC74VHC4051DTR2G
- MC74VHC4052DR2G
- MC74VHC4052DTR2
- MC74VHC4052DTR2G
- MC74VHC4053DR2G
- MC74VHC4053DTR2
- MC74VHC4053DTR2G
- MC74VHC4066DR2G
- MC74VHC4066DTR2
- MC74VHC4066DTR2G
- MC74VHC4316DG
- MC74VHC4316DR2G
- MC74VHC4316DT
- MC74VHC4316DTG
- MC74VHC4316DTR2
- MC74VHC4316DTR2G
- NLSF1174MNR2G
- NLV74HC04ADR2G
- NLV74HC244ADWR2G
- NLV74HC373ADWR2
- NLV74HC4053ADWRG
- NLV74HC541ADWR2
- NLV74HC573ADWR2
- NLV74HCT541ADWG
- NLV74HCT541ADWRG
- NLV74HCT573ADWR2
- NLV74HCT574ADWRG
- NLVHC165ADR2G
- NLVHC4051ADWR2G
- NLVHC4851ADR2G
- NLVHC4851ADTR2G
- SC74HC595ADTR2G
- SL000HC574ANG